



Product Marking Change For Virtex-II, Virtex-II Pro and Virtex-4 FPGA Flip Chip Top Mark Ink To Laser Transition

XCN14019 (v1.1) June 18, 2014

Product Change Notice – For Information Only

Overview

The purpose of this notification is to advise customers of a product marking change for Virtex®-II, Virtex®-II Pro, and Virtex®-4 FPGA Flip Chip packages. There is no change to the form, fit, or function.

Description

Xilinx will be converting the package top mark from ink to laser mark for all Virtex-II, Virtex-II Pro, and Virtex-4 FPGA Flip Chip packages.

Products Affected

This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade including HiRel (XQ) devices. In addition, all associated specification control document (SCD) devices are affected as well. Affected device combinations are included in the following Tables:

- [Virtex-II and Virtex-II Pro FPGA Flip Chip Device Products Affected](#)
- [Virtex-4 FPGA Flip Chip Products Affected](#)
- [Hi-Rel \(XQ\) Flip Chip Device Products Affected](#)
- [EasyPath Flip Chip Device Products Affected](#)

Table 1: Virtex-II and Virtex-II Pro FPGA Flip Chip Device Product Affected

Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product
XC2V1000	XC2V4000	XC2VP2	XC2VP30	XC2VP50
XC2V1500	XC2V6000	XC2VP20	XC2VP4	XC2VP7
XC2V2000	XC2V8000	XC2VP100	XC2VP40	XC2VP70
XC2V3000				

Table 2: Virtex-4 FPGA Flip Chip Device Product Affected

Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product
XC4VFX100	XC4VFX40	XC4VLX160	XC4VLX60	XC4VSX55
XC4VFX12	XC4VFX60	XC4VLX200	XC4VLX80	
XC4VFX140	XC4VLX100	XC4VLX25	XC4VSX25	
XC4VFX20	XC4VLX15	XC4VLX40	XC4VSX35	

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Table 3: Hi-Rel (XQ) Flip Chip Device Product Affected

Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product
XQ2V6000	XQ4VFX100	XQ4VLX100	XQ4VLX40	XQ4VSX35
XQ2VP40	XQ4VFX140	XQ4VLX160	XQ4VLX60	XQ4VSX55
XQ2VP70	XQ4VFX60	XQ4VLX25	XQ4VLX80	

Table 4: EasyPath Flip Chip Device Product Affected

Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product
XCE0103	XCE0204	XCE04F10	XCE04L4	XCE04L8
XCE0104	XCE0205	XCE04L10	XCE04L6	XCE04S2
XCE0106	XCE0207			

Key Dates and Ordering Information

Beginning on June 15th, 2014 (date code: 1425), Xilinx will begin crossing shipping devices with either ink or laser mark until all ink inventory is depleted.

Traceability

Affected devices are identified by the following package top marks as shown in the [Figure 1](#) and [Figure 2](#).

Product marking example:

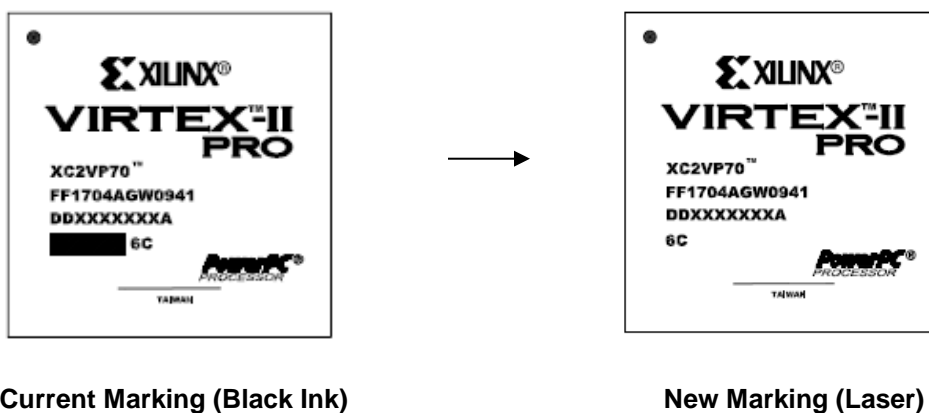


Figure 1

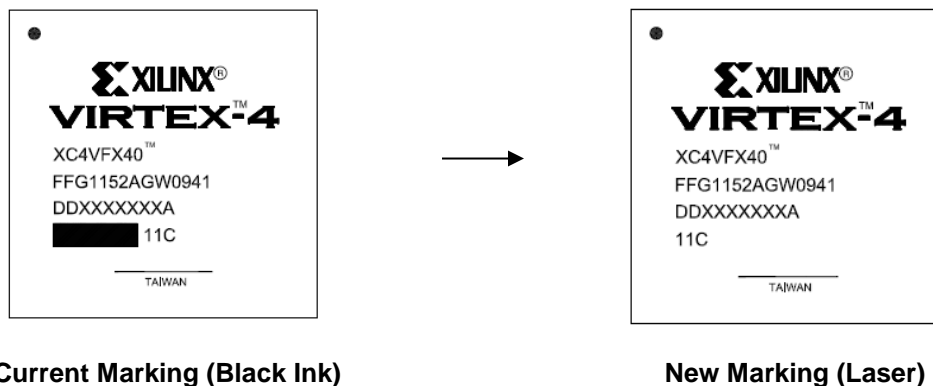


Figure 2

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/16/2014	1.0	Initial release.
06/18/2014	1.1	Remove the wording “adding device trace code” from description.

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